

AMENDMENTS TO THE CLAIMS

This listing of claims replaces all prior listing of claims in this application.

Claims 1-25 (Canceled).

26. (Currently amended) A composition suitable for use in etching an insulative layer formed over a substrate in a semiconductor device, said composition consisting of:

a flowing plasma etchant mixture consisting of at least one fluorocarbon and ammonia, wherein said at least one fluorocarbon and ammonia form a reactive mixture.

27. (Previously presented) The composition of claim 26, wherein said fluorocarbon is at least one member selected from the group consisting of fluorohydrocarbons, chlorofluorocarbons and chlorofluorohydrocarbons.

28. (Original) The composition of claim 27, wherein said fluorocarbon is at least one member selected from the group consisting of C₄F₈, C₄F₆, C₅F₈, CF₄, C₂F₆, C₃F₈, CHF₃, and CH₂F₂.

29. (Original) The composition of claim 26, wherein said fluorocarbon is at least one member selected from the group consisting of CF₄, CHF₃, and CH₂F₂.

30. (Original) The composition of claim 29, wherein said fluorocarbon is at least two members selected from the group consisting of CF₄, CHF₃, and CH₂F₂.

31. (Original) The composition of claim 30, wherein said fluorocarbon is a combination of CF₄, CHF₃, and CH₂F₂.

32. (Previously presented) The composition of claim 26, wherein said composition is ineffective to remove side wall spacers of a gate stack formed over said substrate.

Claims 33-70 (Canceled).

71. (Currently amended) A composition suitable for use in etching an insulative layer formed on a substrate in a semiconductor device, said composition consisting of:

a plasma etchant mixture consisting of ~~at least two fluorocarbons~~ CF₄, at least one other fluorocarbon, and NH₃, wherein said CF₄, at least one other fluorocarbon, and NH₃ form a reactive mixture.

Claims 72-76 (Canceled).

77. (Currently amended) A composition suitable for use in etching an insulative layer formed over a substrate in a semiconductor device, said composition consisting of:

a gaseous etchant mixture consisting of at least one fluorocarbon and ammonia, wherein said at least one fluorocarbon and ammonia form a reactive mixture.